



EuroCPS

Cyber-Physical Systems

A network of design centers boosting and initiating synergies between Innovative companies, major CPS-platforms and CPS-competency providers

ICT1-clustering and communication event

Ph.Bonnot, Vienna, April 14, 2016



Smart Anything Everywere initiative



Innovation Services for
European Smartization by SMEs
Coordinator: Blumorpho



Smart Access to Manufacturing for
Systems Integration
Coordinator: Hahn-Schickard Ges.



CPS Engineering Labs
Coordinator: Fortiss



Industrial access to CPS
technologies and competencies
Coordinator: CEA-Leti

➔ >25M€ of funding invested by the European Commission to
catch the CPS market

EuroCPS in a nutshell

- Call: ICT-01-2014
- Launched: Feb 1st, 2015
- Duration: 3 years

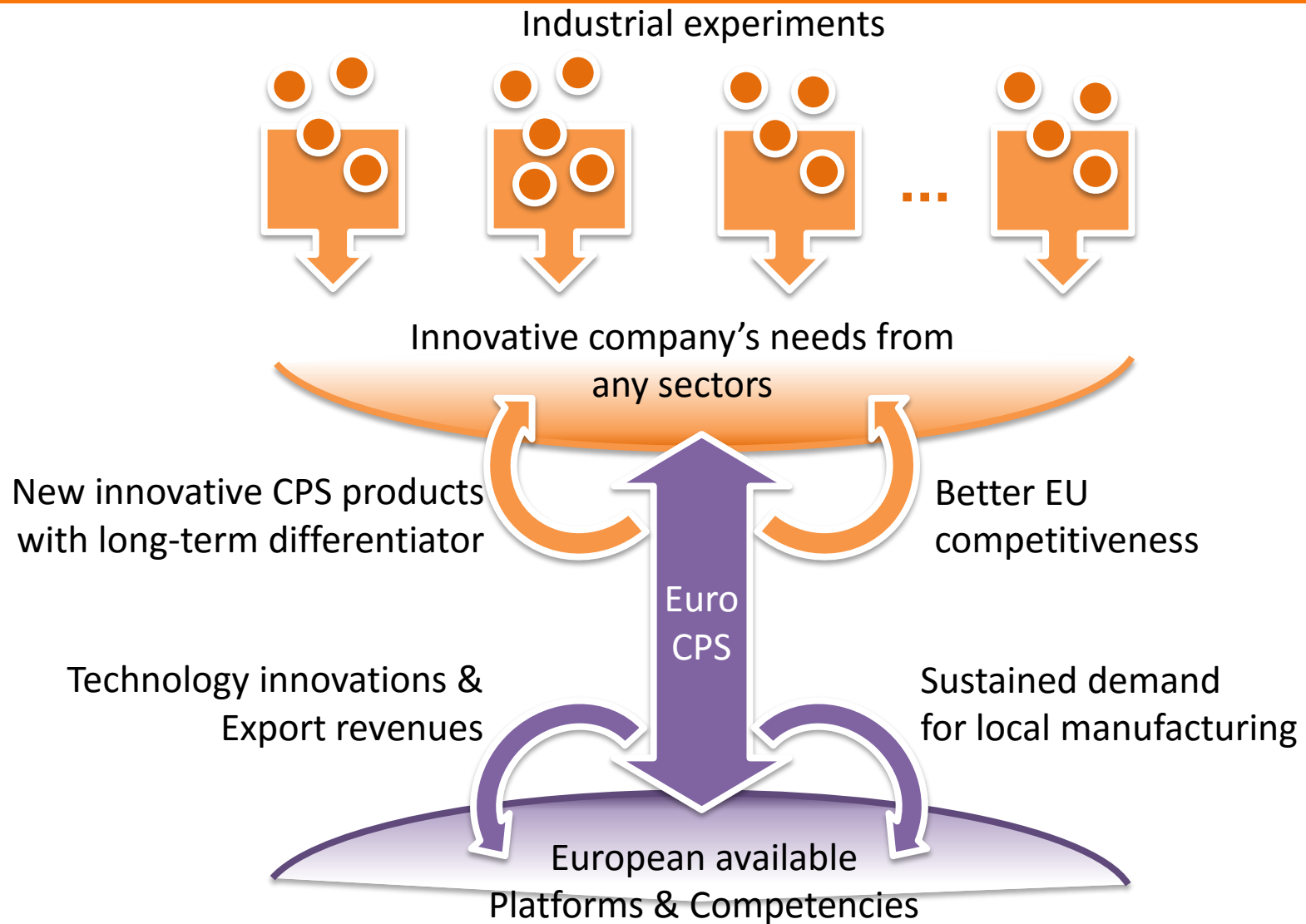
- 9 Countries
- 15 Partners
- 8 Technology Platforms

- Budget: 9,178,641€
- EC funding: 8,186,835€



➔ **Industrial Experiment support: 76% of the EuroCPS funding**

EuroCPS objectives



EuroCPS mission

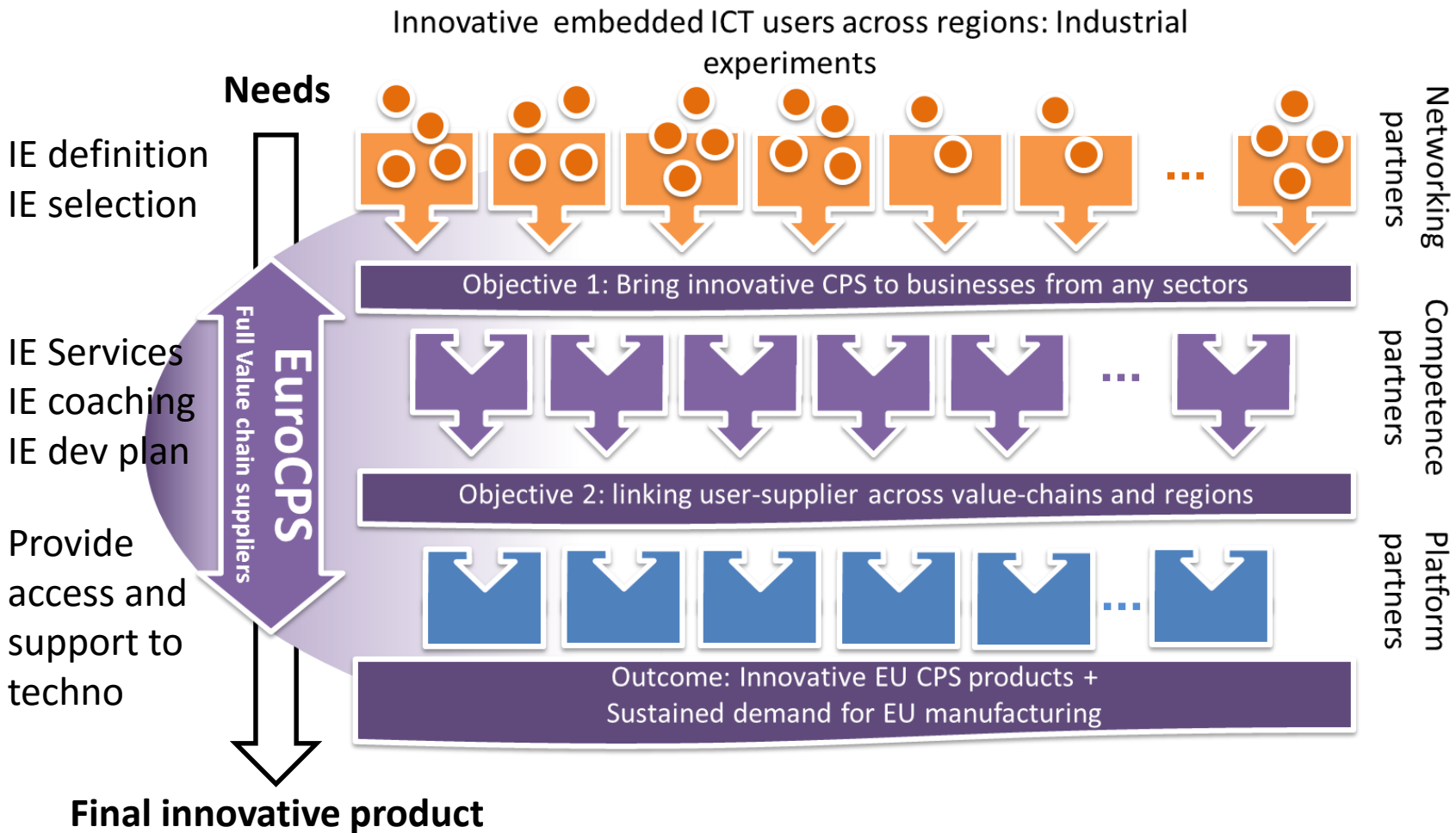
- **Provide an easy path to build innovative CPS systems** to SMEs from any sector
 - Leverage the existing regional ecosystem across the full value chain and range of competencies
- **Facilitates user-supplier partnerships** across value chains and regions
 - One-stop-shop providing a critical mass of technologies and competencies
- **Enable a new cooperation model** linking software, system and nano-electronic industries along the full CPS value chain
 - Industrial experiments initiated and led by SMEs

➔ Reduce development time and certification efforts



EuroCPS structure

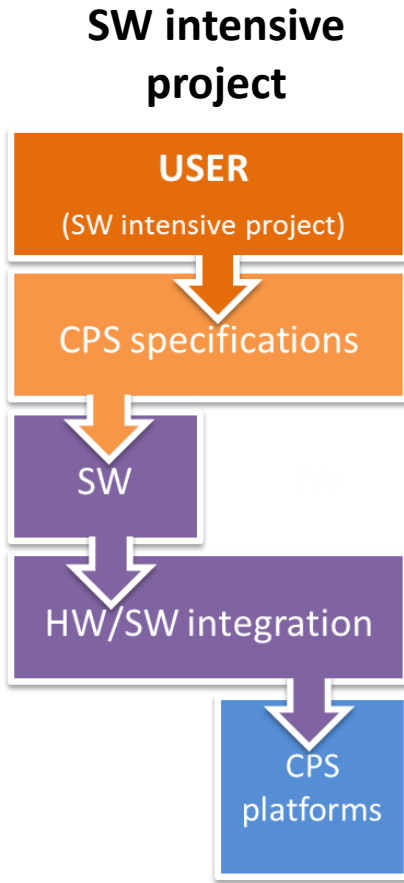
Beneficiaries (CA)



➡ Supported, managed and monitored by project partners

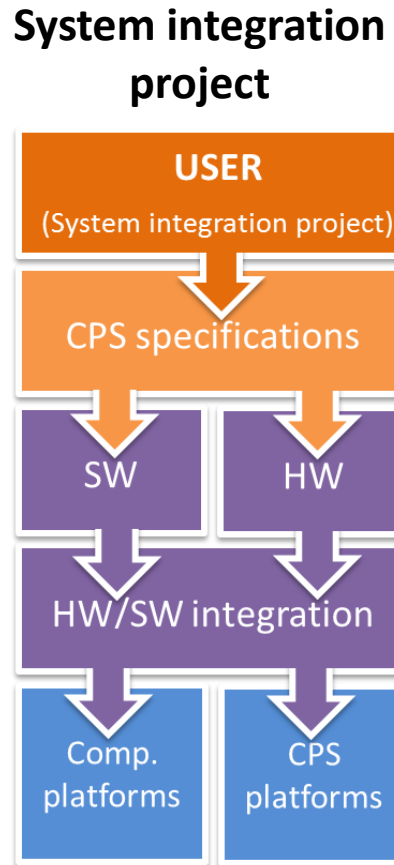
EuroCPS Industrial Experiments

Solution using existing prog. platforms



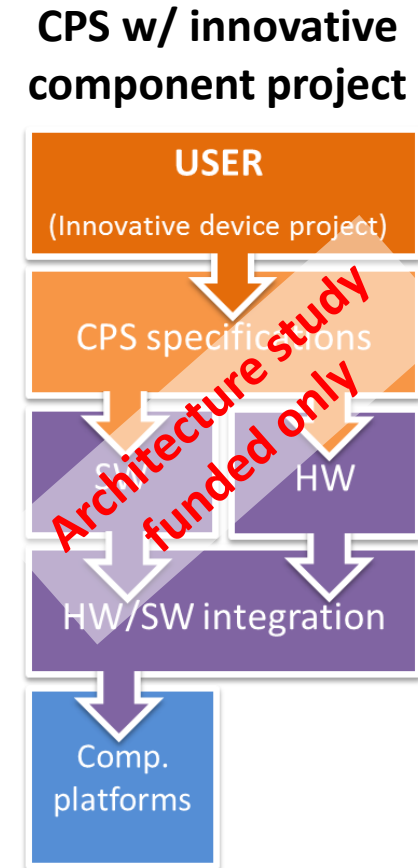
➔ SW prototype demonstrator

Solution using existing SW & HW components



➔ Integrated system prototype demonstrator

Solution using specific SW & HW components



➔ System architecture virtual prototype demonstrator



The 8 EuroCPS platforms

Software



Avionics Platform

Processing board & real time SW solutions provided by Thales



Integrated and Open Development Platform

Simulation methods and tools for development provided by AVL

Integration system



Connectivity Platform

Solution for digitalization application provided by Schneider



STM32 Microcontroller Platform

32-bit product range provided by STMicroelectronics



iNEMO Inertial Platform

A sensor platform provided by STMicroelectronics



Quark System on Chip Platform

Low-power platform provided by Intel

Hardware



Power management Platform

Component platform provided by Infineon

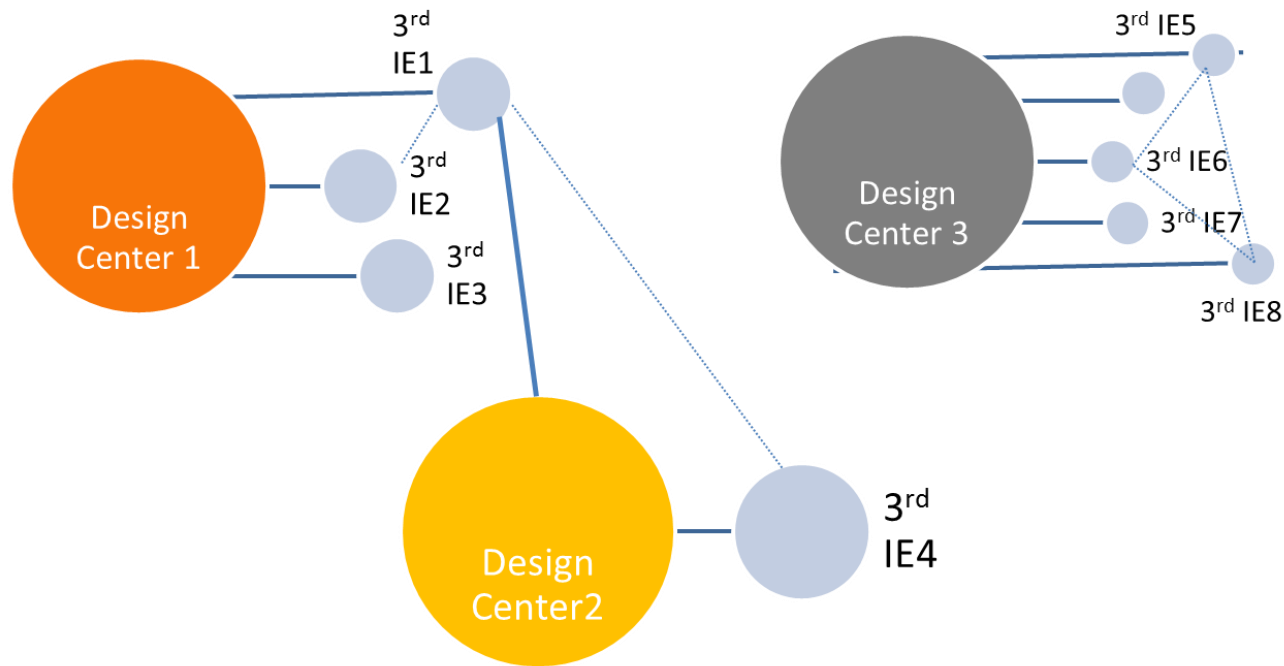


Silicon Process and Package Technology

Leading-edge silicon processes and package technologies provided by STMicroelectronics

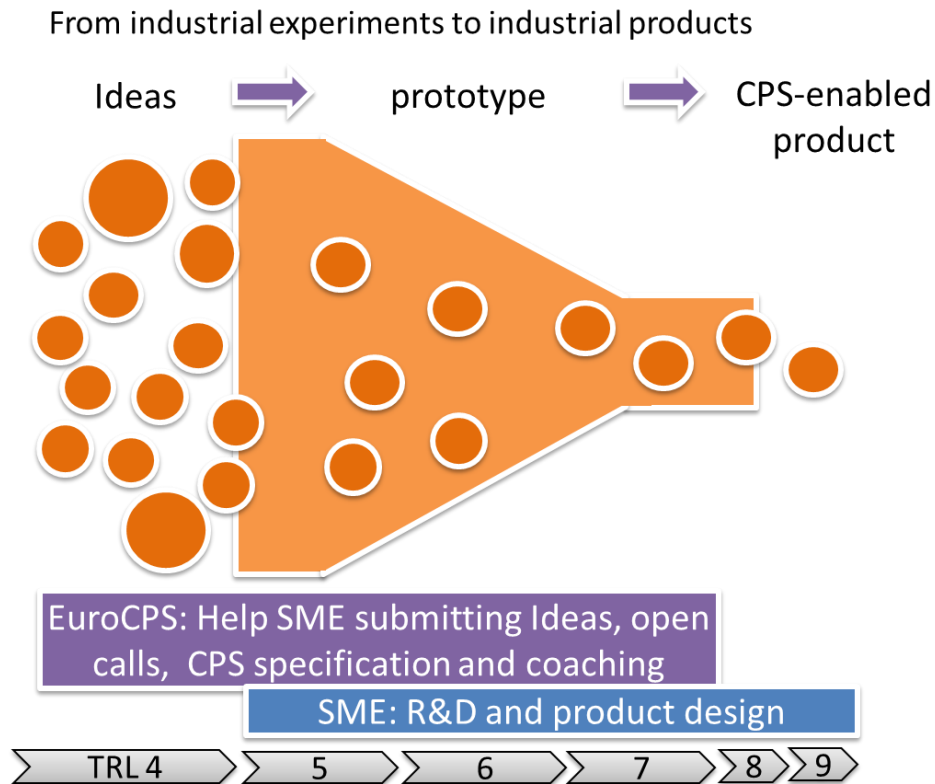


EuroCPS SME financial support



- ➔ Cascade funding (70% of the budget): Support R&D work of 3rd parties
- + Platform funding: Support the technology access
- + Competence funding: Support the expertise, know-how access

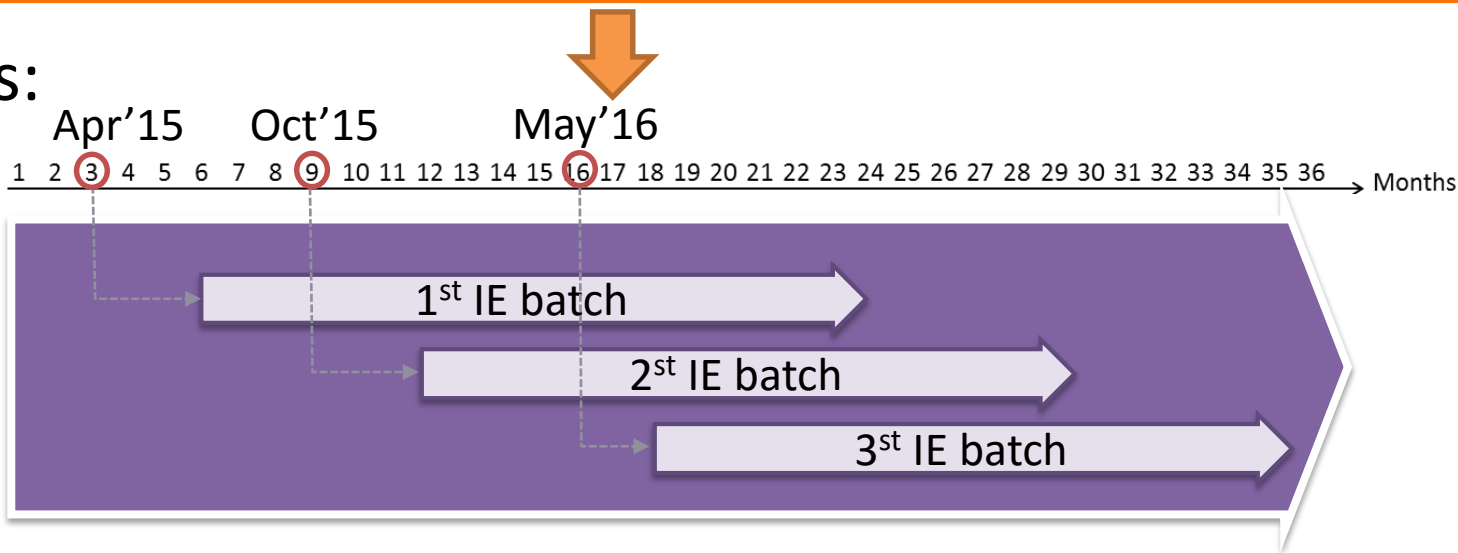
EuroCPS industrial experiments



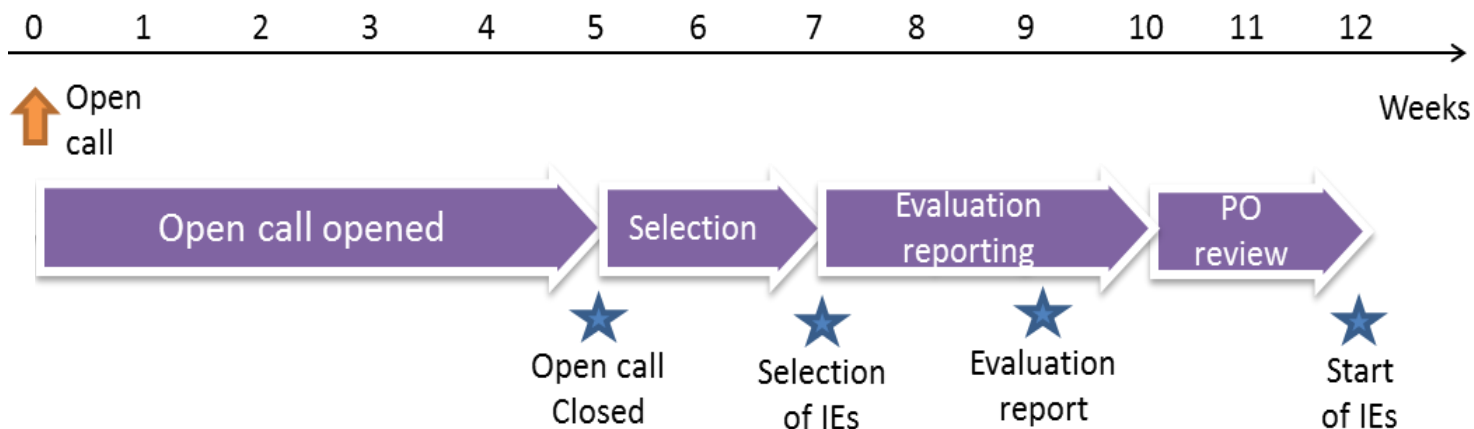
- ➔ Project criteria: Excellence, Impact, Quality
- ➔ Fast track experiments (18 months maximum)

EuroCPS open calls

Dates:



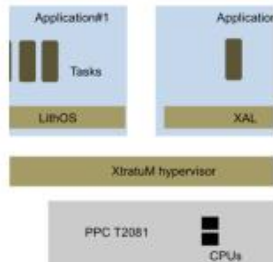
Basic principal:



EuroCPS 1st and 2nd call IEs



Innovation Branding Through Trusted IoT IBT3



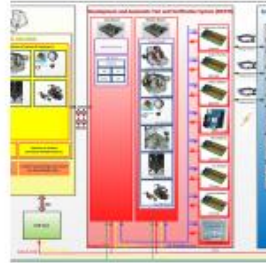
Mixed Critical Avionics on Multicore Xtratum Hypervisor (MCS-MX)



Mb/s Green-OFDM IoT



SmartLAB - Sample Management with RFID Tags for Laboratories



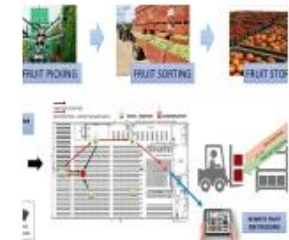
Development and Automatic Test and Verification System (DATVS)



SmartSSL



GUDA - Multifunctional graphical universal data display



Localization and Tracking with inertial sensors for agri-food applications (LTIS)



WEETSY2 - Wearable Eye Tracking System V2

➡ 72 proposals, 24 granted IEs

Thank you

www.eurocps.org

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